

ABSTRACT

SILICA SPHERICAL PARTICLES FOR SEMICONDUCTOR SEALING

MATERIAL

The purpose of the present invention is to provide: silica particles of which the maximum particle diameter can be minimized and which can achieve proper fluidability that cannot be achieved by the conventional techniques; and silica spherical particles which, when used as a filler for a heat-dissipating sheet, can achieve excellent heat conductivity and flexibility. Silica spherical particles characterized in that, when particles each having a size of 5 μm or more and imaged by an optical measurement are observed, the particle diameter of each of the particles, which is determined from the image, satisfies the following requirements. Requirements: $D_{99} \leq 29 \mu\text{m}$, and $10 \mu\text{m} \leq D_{\text{mode}} < D_{99}$, and $D_{99}/D_{\text{mode}} \leq 1.5$, and $D_{\text{mode}} \leq 20 \mu\text{m}$.

Fig.1